

Amendments to the Specification:

Please insert the following paragraph after paragraph [0018]:

Figure 9 is a schematic cross-sectional view illustrating a microelectronic device set configured in accordance with an embodiment of the disclosure.

Please insert the following paragraph after paragraph [0040]:

Figure 9 schematically illustrates a microelectronic device set comprised of the first microelectronic device 210b and a second microelectronic device 920. In the illustrated embodiment, the second microelectronic device 920 includes a second die 912 with a second integrated circuit 914 electrically coupled to a second bond-pad 916. The second bond pad 916 can be electrically coupled to the conductive interconnect 546 and the first bond pad 216 by, for example, re-melting or reflowing a portion of the conductive plug 560 and/or using other suitable connection methods known in the art.